



Material Content Data Sheet



Sales Product Name		TLE8110ED		Issued		1. August 2018		
MA#		MA001647650						
Package		PG-DSO-36-72		Weight*		538.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.286	2.28	2.28	22804	22804
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		448	
	non noble metal	copper	7440-50-8	240.973	44.74	44.79	447279	447861
	non noble metal	copper	7440-50-8	2.585	0.48	0.48	4797	4797
wire	non noble metal	copper	7440-50-8	2.585	0.48	0.48	4797	4797
encapsulation	organic material	carbon black	1333-86-4	0.814	0.15		1511	
	plastics	epoxy resin	-	31.747	5.89		58926	
	inorganic material	silicondioxide	60676-86-0	238.780	44.32	50.36	443207	503644
leadfinish	non noble metal	tin	7440-31-5	6.656	1.24	1.24	12354	12354
plating	noble metal	silver	7440-22-4	1.799	0.33	0.33	3340	3340
glue	plastics	epoxy resin	-	0.490	0.09		910	
	noble metal	silver	7440-22-4	2.311	0.43	0.52	4290	5200
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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